

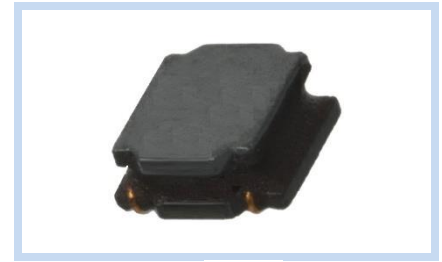
Power Inductor SMD Low Profile, High Current AEC-Q200

PIW-6045M65

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FEATURE

- Magnetic Shield Construction for Power Circuit.
- Large Current and Low DC Resistance
- Low Profile Power Inductors
- Application: DC/DC Converter, Battery Powered Devices, Low Profile High Current Power Supply, Notebook/Server
- AEC-Q200 Compliant



ELECTRICAL CHARACTERISTICS

Part Number	Inductance (μH)	Tolerance Code	Test Frequency (Hz)	DCR ±20% (mΩ)	I _{SAT} (A)	I _{RMS} (A)
PIWR36□6045M65	0.36	M, Y	1MHz/1V	4.8	18.00	9.00
PIWR47□6045M65	0.47	M, Y	1MHz/1V	6.8	17.00	8.60
PIWR82□6045M65	0.82	M, Y	1MHz/1V	8.5	14.50	8.20
PIW1R0□6045M65	1.00	M, Y	1MHz/1V	10.0	13.50	8.00
PIW1R2□6045M65	1.20	M, Y	1MHz/1V	10.5	12.50	7.50
PIW1R3□6045M65	1.30	M, Y	1MHz/1V	10.5	12.50	7.50
PIW1R5□6045M65	1.50	M, Y	1MHz/1V	11.7	12.00	7.00
PIW1R8□6045M65	1.80	M, Y	1MHz/1V	12.0	11.00	6.80
PIW2R0□6045M65	2.00	M, Y	1MHz/1V	13.5	10.50	6.50
PIW2R2□6045M65	2.20	M, Y	1MHz/1V	15.0	9.50	6.00
PIW2R3□6045M65	2.30	M, Y	1MHz/1V	16.0	9.30	5.80
PIW3R0□6045M65	3.00	M, Y	1MHz/1V	20.0	8.00	5.20
PIW3R3□6045M65	3.30	M, Y	1MHz/1V	21.0	7.80	5.00
PIW3R6□6045M65	3.60	M, Y	1MHz/1V	22.5	7.40	4.90
PIW4R7□6045M65	4.70	L, M, Y	1MHz/1V	26.0	6.80	4.50
PIW5R6□6045M65	5.60	L, M, Y	1MHz/1V	31.0	6.40	4.10
PIW6R3□6045M65	6.30	L, M, Y	1MHz/1V	33.0	5.90	3.80
PIW6R8□6045M65	6.80	L, M, Y	1MHz/1V	34.0	5.70	3.60
PIW8R2□6045M65	8.20	L, M, Y	1MHz/1V	46.0	5.10	3.40
PIW100□6045M65	10.0	K, L, M, Y	1MHz/1V	52.0	4.60	3.20
PIW150□6045M65	15.0	K, L, M, Y	1MHz/1V	71.0	3.80	2.80
PIW180□6045M65	18.0	K, L, M, Y	1MHz/1V	80.0	3.40	2.60
PIW220□6045M65	22.0	K, L, M, Y	1MHz/1V	96.0	3.30	2.30
PIW330□6045M65	33.0	K, L, M, Y	1MHz/1V	145	2.50	1.80
PIW470□6045M65	47.0	K, L, M, Y	1MHz/1V	200	2.00	1.60
PIW560□6045M65	56.0	K, L, M, Y	1MHz/1V	230	1.80	1.40
PIW680□6045M65	68.0	K, L, M, Y	1MHz/1V	305	1.60	1.10
PIW820□6045M65	82.0	K, L, M, Y	1MHz/1V	365	1.50	0.98
PIW101□6045M65	100	K, L, M, Y	1MHz/1V	456	1.33	0.92
PIW121□6045M65	120	K, L, M, Y	1MHz/1V	500	1.20	0.85
PIW151□6045M65	150	K, L, M, Y	1MHz/1V	626	1.10	0.75
PIW181□6045M65	180	K, L, M, Y	1MHz/1V	745	1.00	0.68
PIW221□6045M65	220	K, L, M, Y	1MHz/1V	900	0.88	0.60
PIW331□6045M65	330	K, L, M, Y	1MHz/1V	1400	0.60	0.55
PIW471□6045M65	470	K, L, M, Y	1MHz/1V	2050	0.50	0.40

Notes:

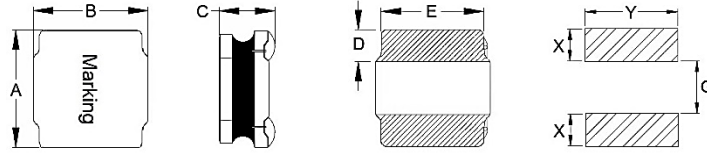
1. All test data referenced to 25°C ambient.
2. Saturation Current (I_{sat}) based on inductance drop ($\Delta L/L0$: $\leq 30\%$) approximately
3. Heat Rated Current (I_{rms}) based on temperature rise (ΔT : 40 °C) approximately
4. □: Tolerance Code Ratings: K = $\pm 10\%$, L = $\pm 15\%$, M = $\pm 20\%$, Y = $\pm 30\%$
5. Operating Temperature: -55°C ~ +125°C (Including Self-temperature rise)

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DIMENSIONS

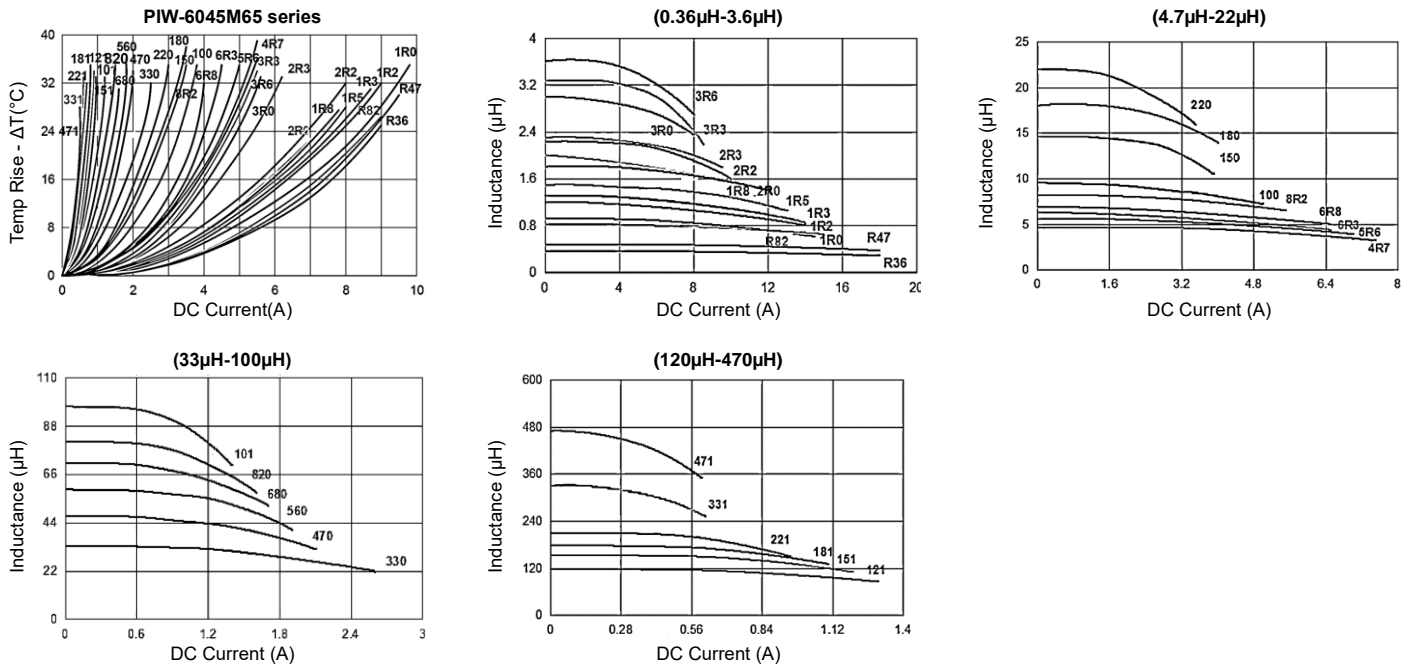


Size Code	A	B	C	D	E	X	Y	G
6045	6.0 ±0.3	6.0 ±0.3	4.2 ±0.3	1.9 ±0.3	4.8 ±0.3	3.0	6.3	2.5

Unit: mm

Notes: 1. The above PCB layout reference only. 2. Recommend solder paste thickness at 0.15mm and above.

CHARACTERISTIC CURVES- PIW-6045M65 series



PART NUMBERING SYSTEM

PIW 471M 6045 M65
(1) (2) (3) (4)

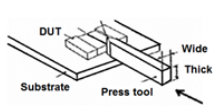
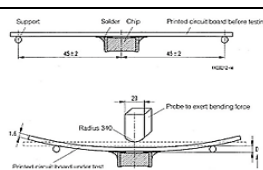
No	Item	Code	Description
(1)	Product Code	PIW	Power Inductor series, Wire Wound type
(2)	Inductance	471M	470 μH ±20%(M) First two digits: significant, Third: multiplier
(3)	Size Code	6045	6.0x6.0x4.2 mm Length x Width x Thickness (mm)
(4)	Series Code	M65	Surface Mount Shielded, Low Profile, High Current series, AEC-Q200 Compliant

Power Inductor SMD Low Profile, High Current AEC-Q200

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RELIABILITY TEST CONDITON AND REQUIREMENT

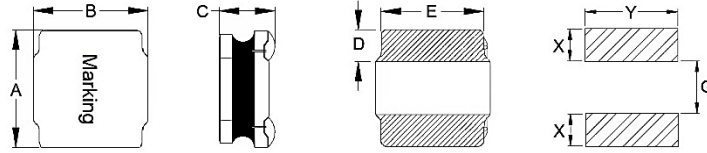
Item	Test Standards / Conditions / Equipment	Requirement															
Inductance	HP4284A, CH11025, CH3302, CH1320, CH1320S, LCR Meter	Refer to specification															
DC Resistance	CH16502, Agilent33420A Micro-Ohm Meter	Refer to specification															
Mechanical Shock	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi) ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> <tr> <td>Lead</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi) ft/sec	SMD	100	6	Half-sine	12.3	Lead	100	6	Half-sine	12.3	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value
	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi) ft/sec												
SMD	100	6	Half-sine	12.3													
Lead	100	6	Half-sine	12.3													
Solderability	Method B1, 4 Hrs at 155°C dry heat at 255°C $\pm 5^\circ\text{C}$ Test Time: 5 +0/-0.5 seconds. Method D category 3. (steam aging 8 hours $\pm 15\text{min}$) at 260°C $\pm 5^\circ\text{C}$ Test Time: 30+0/-0.5 seconds.	More than 95% of the terminal electrode should be covered with solder.															
Resistance to Soldering Heat	Solder temperature: 260 $\pm 5^\circ\text{C}$ for 10 seconds Temperature ramp/immersion and emersion rate 25mm/s ± 6 mm/s. Completely cover the termination.	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															
Vibration	Oscillation Frequency: 10~2K~10 Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 1.52mm $\pm 10\%$ Testing Time: 12 hours (20 minutes, 12 cycles each of 3 orientations)																
High Temperature Exposure	Temperature: 125 $\pm 2^\circ\text{C}$ Duration 1000Hrs Min Measured at room temperature after placing for 24 ± 2 hrs	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															
Biased Humidity	Humidity: 85 $\pm 3\%$ R.H. Temperature: 85°C $\pm 2^\circ\text{C}$ Duration: 1000Hrs Min Measured at Room Temperature after placing for 24 ± 2 hrs																
High Temperature Operational Life	Temperature: 125 $\pm 2^\circ\text{C}$ Duration: 1000Hrs Min. with 100% rated current Measured at Room Temperature after placing for 24 ± 2 Hrs																
Temperature Cycling	Condition for 1 cycle <table border="1"> <thead> <tr> <th>Step</th> <th>1</th> <th>2</th> <th>3</th> <th>4</th> </tr> </thead> <tbody> <tr> <td>Temperature</td> <td>-55 $\pm 2^\circ\text{C}$</td> <td>125 $\pm 2^\circ\text{C}$</td> <td>125 $\pm 2^\circ\text{C}$</td> <td>Low Temp</td> </tr> <tr> <td>Duration</td> <td>30min Min</td> <td>1 min Max</td> <td>30 min Min</td> <td>1 min Max</td> </tr> </tbody> </table> Number of Cycle: 1000 Measured at room temperature after placing for 24 ± 2 hrs	Step	1	2	3	4	Temperature	-55 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	Low Temp	Duration	30min Min	1 min Max	30 min Min	1 min Max	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value
	Step	1	2	3	4												
Temperature	-55 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	Low Temp													
Duration	30min Min	1 min Max	30 min Min	1 min Max													
Thermal Shock	Condition for 1 cycle <table border="1"> <thead> <tr> <th>Step</th> <th>1</th> <th>2</th> <th>3</th> </tr> </thead> <tbody> <tr> <td>Temperature</td> <td>-55 $\pm 2^\circ\text{C}$</td> <td>125 $\pm 2^\circ\text{C}$</td> <td>125 $\pm 2^\circ\text{C}$</td> </tr> <tr> <td>Duration</td> <td>15± 1min</td> <td>20sec</td> <td>15± 1min</td> </tr> </tbody> </table> Number of cycles : 300 Measured at room temperature after placing for 24 ± 2 hrs.	Step	1	2	3	Temperature	-55 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	Duration	15 ± 1 min	20sec	15 ± 1 min	Appearance: No damage Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value			
	Step	1	2	3													
Temperature	-55 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$	125 $\pm 2^\circ\text{C}$														
Duration	15 ± 1 min	20sec	15 ± 1 min														
ESD	AEC-Q200-002 HBM ESD, Contact Discharge Level: 4KV (Level 2)	Appearance: No damage															
Resistance to Solvents	Add aqueous wash chemical - OKEM clean or equivalent.	Appearance : No damage															
Terminal Strength	Component mounted on a PCB apply a force 1.8kg to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested. 	Appearance : No damage															
Board Flex	Place the 100x40mm board into a fixture with the component facing down. Apply a force which will bend the board (D) x = 2mm minimum. Duration: 60 (+5) seconds. The Force is to be applied only once to the board 	Appearance : No damage															
Flammability	Electrical Test not Required	V-0 or V-1 are acceptable.															

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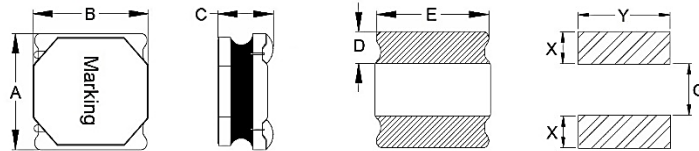
DIMENSIONS- PIW-M65 series



Unit: mm

Size Code	A	B	C	D	E	X	Y	G
3010	3.0 ±0.2	3.0 ±0.2	0.9 ±0.1	0.9 ±0.3	2.7 ±0.3	1.25	3.5	0.9
3012	3.0 ±0.2	3.0 ±0.2	1.0 ±0.2	0.9 ±0.3	2.7 ±0.3	1.25	3.5	0.9
3015	3.0 ±0.2	3.0 ±0.2	1.3 ±0.2	0.9 ±0.3	2.7 ±0.3	1.25	3.5	0.9
6045	6.0 ±0.3	6.0 ±0.3	4.2 ±0.3	1.9 ±0.3	4.8 ±0.3	3.0	6.3	2.5
8040 (< 1.0 μH)	8.0 ±0.3	8.0 ±0.3	4.2 Max	2.4 ±0.3	6.3 ±0.3	2.85	6.6	2.8
8040 (≥ 1.0 μH)	8.0 ±0.3	8.0 ±0.3	3.7 ±0.3	2.4 ±0.3	6.3 ±0.3	2.85	6.6	2.8

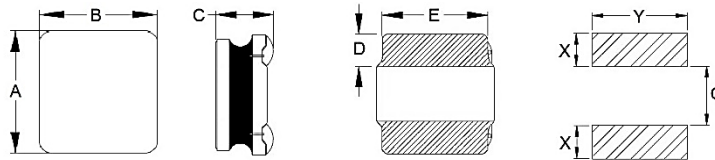
Notes: 1. The above PCB layout reference only. 2. Recommend solder paste thickness at 0.15mm and above.



Unit: mm

Size Code	A	B	C	D	E	X	Y	G
3612	3.6 ±0.2	3.6 ±0.2	1.0 ±0.2	1.2 ±0.3	3.2 ±0.3	0.9	3.7	2.0
4010	4.0 ±0.2	4.0 ±0.2	0.9 ±0.1	1.2 ±0.3	3.5 ±0.3	1.5	4.5	1.5
4012	4.0 ±0.2	4.0 ±0.2	1.0 ±0.2	1.2 ±0.3	3.5 ±0.3	1.5	4.5	1.5
4018	4.0 ±0.2	4.0 ±0.2	1.6 ±0.2	1.1 ±0.2	3.5 ±0.3	1.5	4.5	1.5
4020	4.0 ±0.2	4.0 ±0.2	1.8 ±0.2	1.2 ±0.3	3.4 ±0.3	1.5	4.5	1.5
4030	4.0 ±0.2	4.0 ±0.2	3.0 Max.	1.35 ±0.3	3.4 ±0.4	1.5	3.7	1.3
5010	5.0 ±0.2	5.0 ±0.2	0.9 ±0.1	1.5 ±0.3	4.0 ±0.3	1.85	5.5	1.8
5012	5.0 ±0.2	5.0 ±0.2	1.0 ±0.2	1.5 ±0.3	4.0 ±0.3	1.85	5.5	1.8
5020	5.0 ±0.2	5.0 ±0.2	1.8 ±0.2	1.3 ±0.2	4.7 ±0.2	1.5	4.7	2.1
5030	5.0 ±0.2	5.0 ±0.2	2.8 ±0.2	1.3 ±0.2	4.7 ±0.3	1.85	5.5	1.8
5040 (≤ 10 μH)	4.95 ±0.2	4.95 ±0.2	3.9 ±0.2	1.3 ±0.2	4.2 ±0.2	1.5	4.2	2.1
5040 (> 10 μH)	4.95 ±0.2	4.95 ±0.2	3.8 ±0.2	1.3 ±0.2	4.2 ±0.2	1.5	4.2	2.1
6020	6.0 ±0.2	6.0 ±0.2	1.8 ±0.2	1.6 ±0.3	5.8 ±0.3	1.8	5.8	2.5
6028	6.0 ±0.2	6.0 ±0.2	2.6 ±0.2	1.6 ±0.3	5.8 ±0.3	1.8	5.8	2.5

Notes: 1. The above PCB layout reference only. 2. Recommend solder paste thickness at 0.15mm and above.



Unit: mm

Size Code	A	B	C	D	E	X	Y	G
2016A	2.0 ±0.2	1.6 ±0.2	0.7 ±0.1	0.7 ±0.3	1.8 ±0.2	1.0	2.1	0.5
2016B	2.0 ±0.2	1.6 ±0.2	0.9 ±0.1	0.7 ±0.3	1.6 ±0.2	1.0	2.1	0.5
2016C	2.0 ±0.2	1.6 ±0.2	1.0 ±0.2	0.7 ±0.3	1.6 ±0.2	1.0	2.1	0.5
2520A	2.5 ±0.2	2.0 ±0.2	0.7 ±0.1	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7
2520B	2.5 ±0.2	2.0 ±0.2	0.9 ±0.1	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7
2520C	2.5 ±0.2	2.0 ±0.2	1.0 ±0.2	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7
3225C	3.2 ±0.2	2.5 ±0.2	1.0 ±0.2	1.0 ±0.3	2.5 ±0.2	1.25	3.0	1.0

Notes: 1. The above PCB layout reference only. 2. Recommend solder paste thickness at 0.15mm and above.

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RECOMMENDED SOLDERING PROFILES

Reflow Condition		
Pre Heat	Temp. Min $T_{s(min)}$	150°C
	Temp. Max $T_{s(max)}$	200°C
	Time (min. to max.) (t_s)	60 ~ 120 seconds
Average ramp up rate (Liquidus Temperature) (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L (Ramp-up rate)		3°C/second max
Reflow	Temp. (T_L)	217°C
	Time (min. to max.) (t_L)	60 ~ 150 seconds
Peak Temperature (T_P)		See table below
Time within 5°C of actual peak Temperature (t_p)		10 seconds max
Ramp-down Rate		6°C/second max
Reflow Times		3 times max

Peak Temperature (T_P)			
Volume	< 350mm ³	350-2000mm ³	> 2000mm ³
Thickness < 1.6mm	260°C	260°C	260°C
Thickness 1.6-2.5mm	260°C	250°C	245°C
Thickness ≥ 2.5mm	250°C	245°C	245°C

*Specifications subject to change without notice

